N-Channel Enhancement Mode Power MOSFET **MX3400**

DESCRIPTION

The MX3400 uses advanced trench technology to provide excellent $R_{DS(ON)}$ and low gate charge. It can be used in a wide variety of applications.

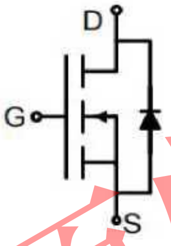
GENERAL FEATURES

- V_{DS}=30V, I_D=5.7A
  $R_{DS(ON)}$(Typ.)=30mΩ @ V_{GS}=2.5V
  $R_{DS(ON)}$(Typ.)=22mΩ @ V_{GS}=4.5V
  $R_{DS(ON)}$(Typ.)=20mΩ @ V_{GS}=10V
- High Power and current handing capability
- Lead free product is acquired
- Surface Mount Package

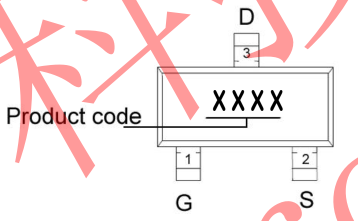
APPLICATION

- PWM applications
- Load switch
- Power management

PINOUT



Schematic diagram



Marking and pin Assignment

SOT-23-3L top view

ORDERING INFORMATION

Part Number	StorageTemperature	Package	Devices Per Reel
MX3400	-55°C to 150°C	SOT-23-3L	3000

ABSOLUTE MAXIMUM RATINGS(T_A=25°C unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	±12	V
Drain Current-Continuous	I_D	5.7	A
Pulsed Drain Current(Note1)	I_{DM}	25	A
Maximum Power Dissipation	P_D	1.4	W
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	°C

THERMAL RESISTANCE

Thermal Resistance, Junction-to-Ambient(Note2)	$R_{\theta JA}$	89	°C/W

Note 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
Note 2. Surface Mounted on FR4 Board, t ≤ 10 sec.

ELECTRICAL CHARACTERISTICS(T_A=25°C unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	V_{GS}=0V, I_D=250μA	30	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS}=30V, V_{GS}=0V	-	-	1	μA
Gate-Body Leakage Current	I_{GSS}	V_{GS}=±12V, V_{DS}=0V	-	-	±100	nA
On Characteristics(Note 3)						
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS}=V_{GS}, I_D=250μA	0.6	0.85	1.4	V
Drain-Source On-State Resistance	$R_{DS(ON)}$	V_{GS}=2.5V, I_D=2A	-	30	50	mΩ
		V_{GS}=4.5V, I_D=3A	-	22	33	mΩ
		V_{GS}=10V, I_D=5.7A	-	20	28	mΩ
Forward Transconductance	g_{FS}	V_{DS}=5V, I_D=5A	10	-	-	S
Dynamic Characteristics(Note4)						
Input Capacitance	C_{iss}	V_{DS}=15V, V_{GS}=0V, F=1.0MHz	-	820	-	pF
Output Capacitance	C_{oss}		-	99	-	pF
Reverse Transfer Capacitance(Note4)	C_{rss}		-	77	-	pF
Switching Characteristics						
Turn-on Delay Time	$t_{d(on)}$	V_{DD}=15V, R_L=2.7Ω, V_{GS}=10V,R_G=3Ω	-	3.3	-	nS
Turn-on Rise Time	t_r		-	4.8	-	nS
Turn-Off Delay Time	$t_{d(off)}$		-	26	-	nS
Turn-Off Fall Time	t_f		-	4	-	nS
Total Gate Charge	Q_g	V_{DS}=15V, I_D=5A, V_{GS}=4.5V	-	9.5	-	nC
Gate-Source Charge	Q_{gs}		-	1.5	-	nC
Gate-Drain Charge	Q_{gd}		-	3	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage(Note 3)	V_{SD}	V_{GS}=0V, I_S=1A	-	-	1.2	V
Diode Forward Current(Note 2)	I_S		-	-	5.7	A

Note 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
Note 3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
Note 4. Guaranteed by design, not subject to product.

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

Figure 1. Switching Test Circuit

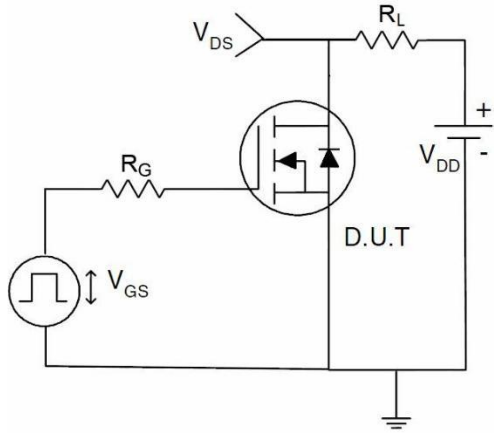


Figure 2. Switching Waveform

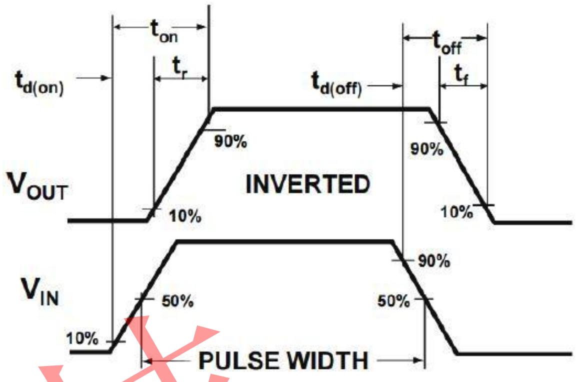


Figure 3. Power Dissipation

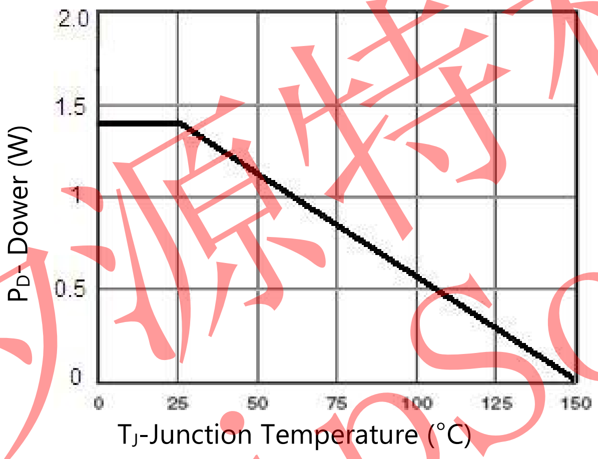


Figure 4. Drain Current

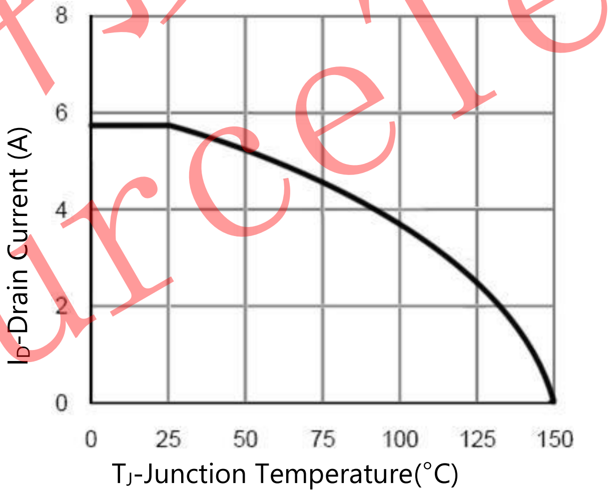


Figure 5. Output Characteristics

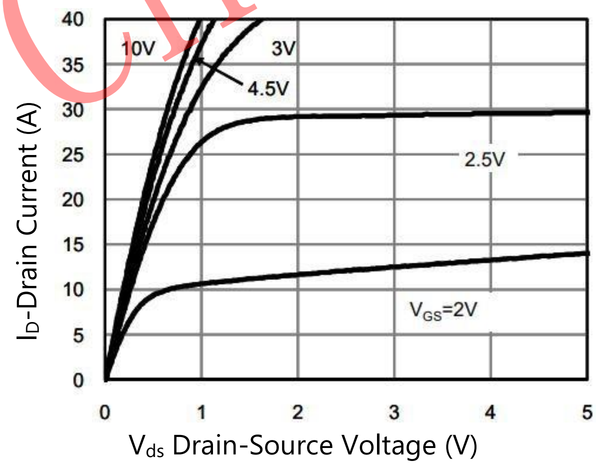
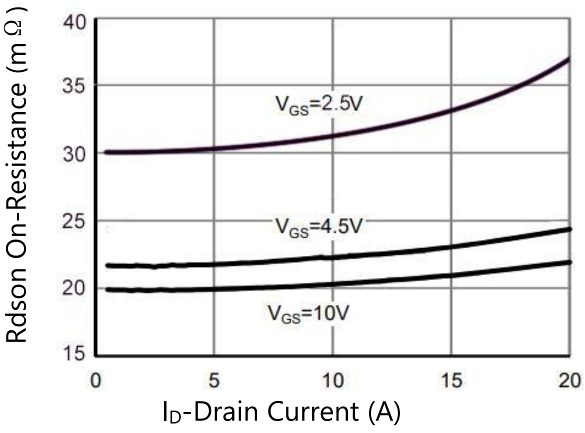


Figure 6. R_{dson} vs Drain Current



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

Figure 7. Transfer Characteristics

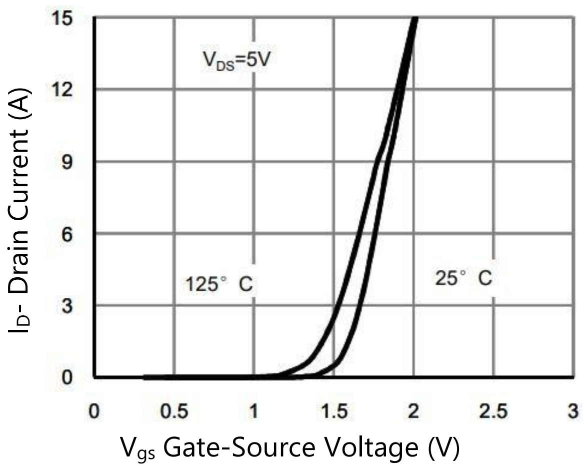


Figure 8. R_{dson} vs Junction Temperature

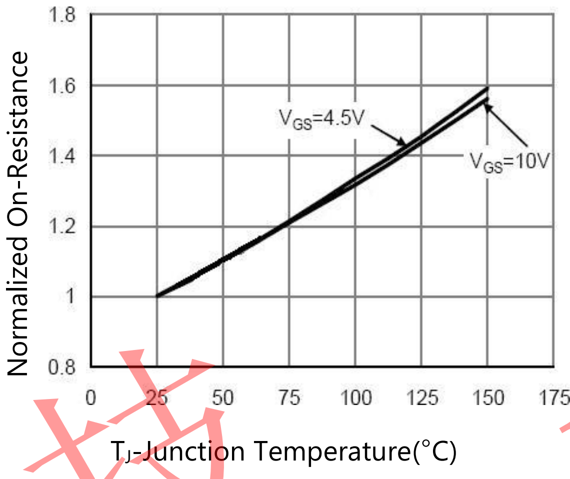


Figure 9. Rdson vs V_{gs}

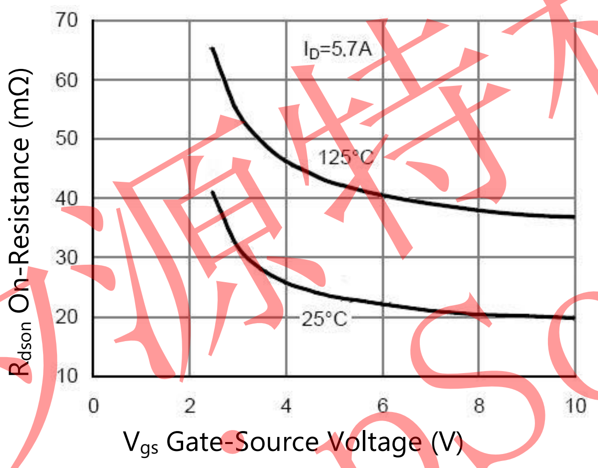


Figure 10. Capacitance vs V_{DS}

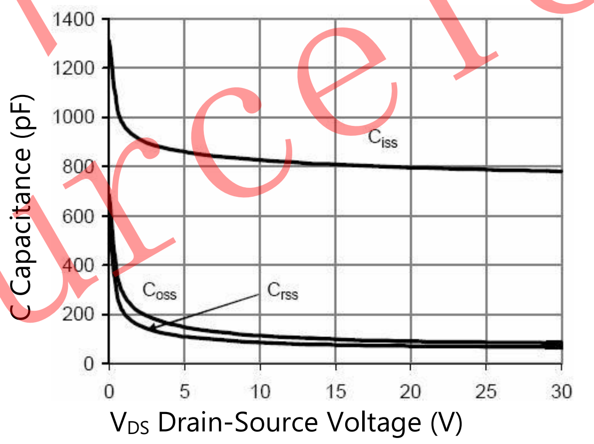


Figure 11. Gate Charge

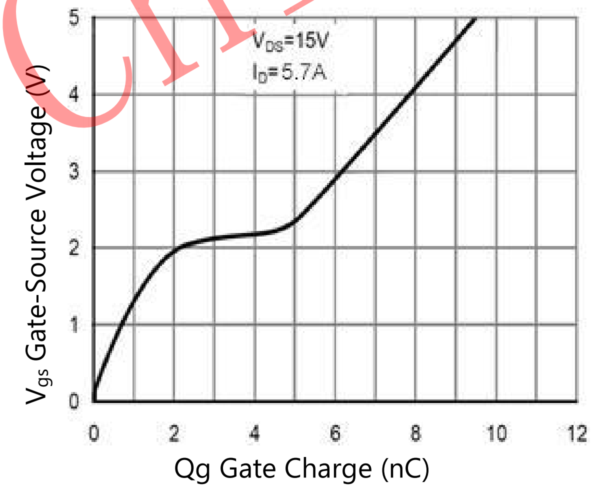
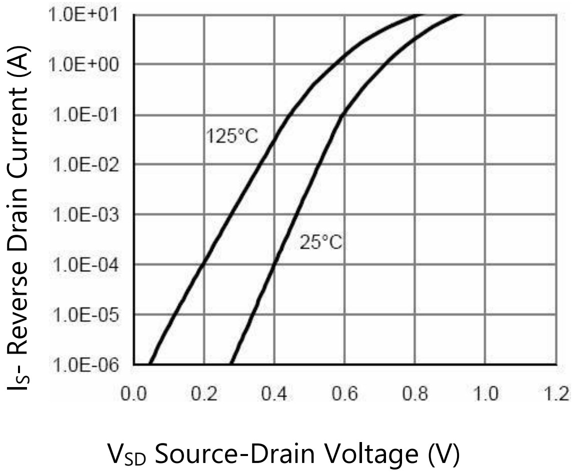


Figure 12. Source- Drain Diode Forward



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

Figure 13. Safe Operation Area

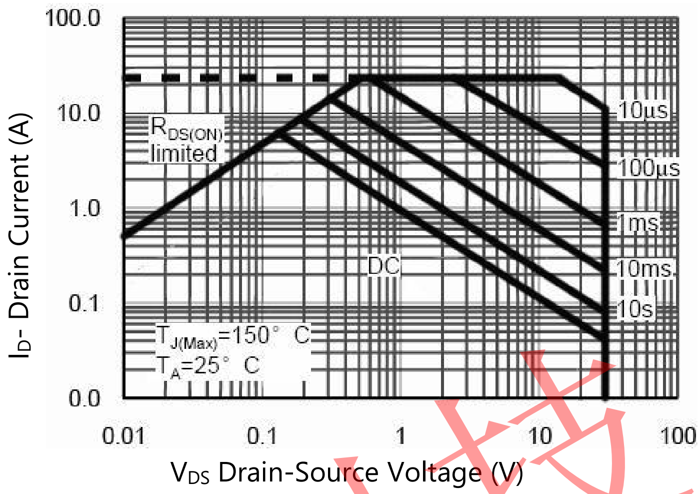
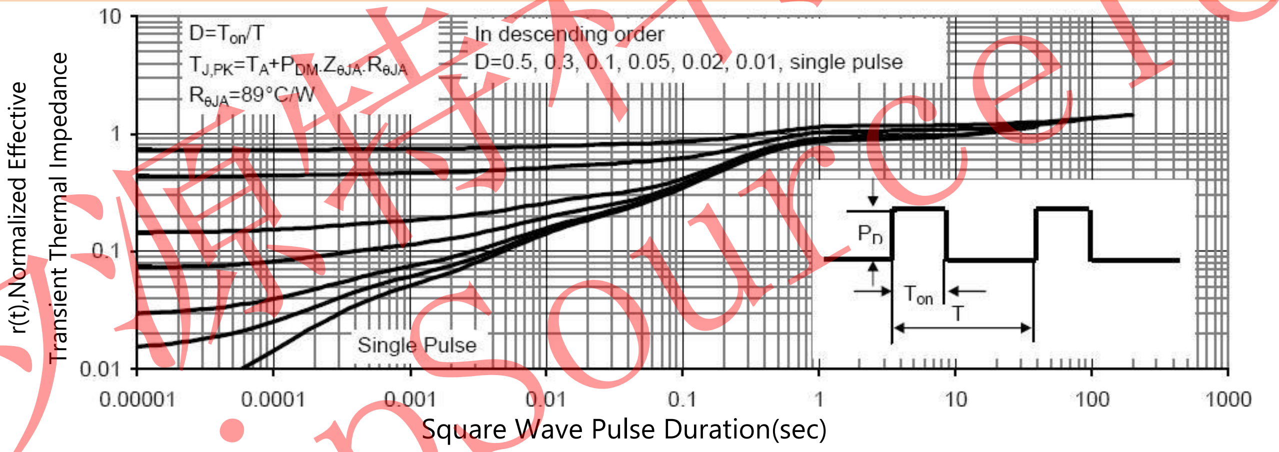
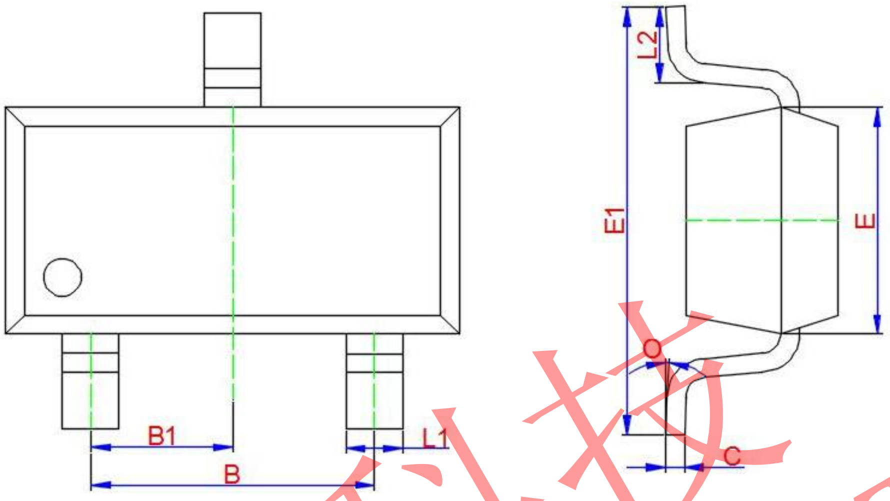


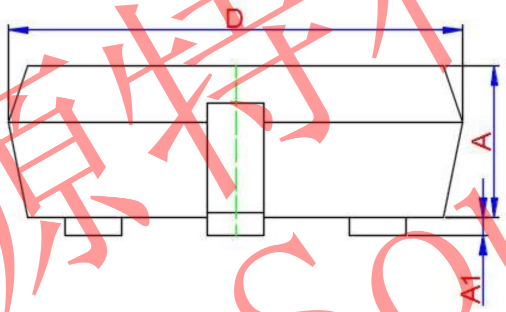
Figure 14. Normalized Maximum Transient Thermal Impedance



PACKAGE INFORMATION

SOT-23-3L





Symbol	Dimensions in Millimeters		
	Min	Typ.	Max
A	1.050	1.100	1.150
A1	0.000	0.050	0.100
L1	0.300	0.400	0.500
C	0.100	0.150	0.200
D	2.820	2.920	3.020
E	1.500	1.600	1.700
E1	2.650	2.800	2.950
B	1.800	1.900	2.000
B1	0.950 TYP.		
L2	0.300	0.450	0.600
O	0°	4°	8°